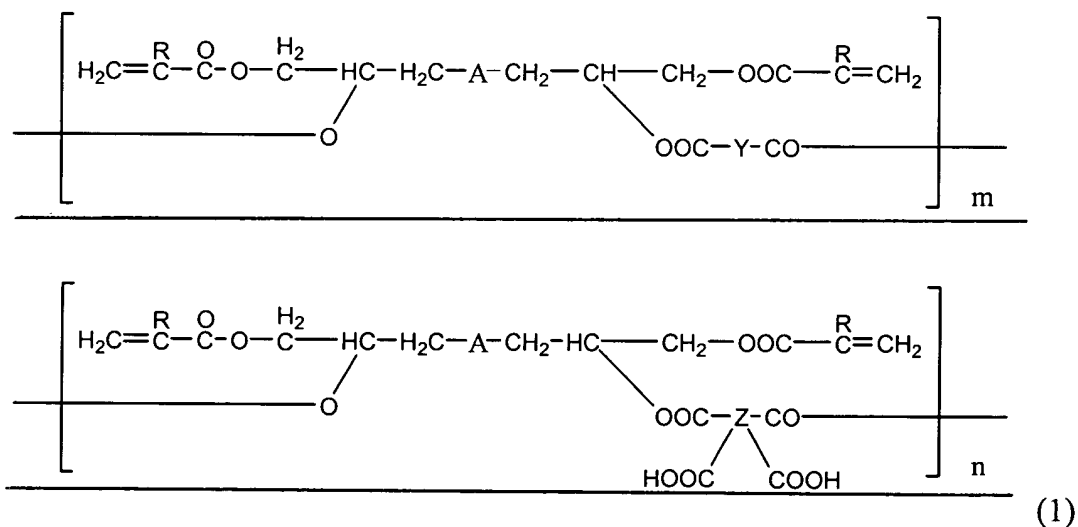


AMENDMENTS TO THE CLAIMS

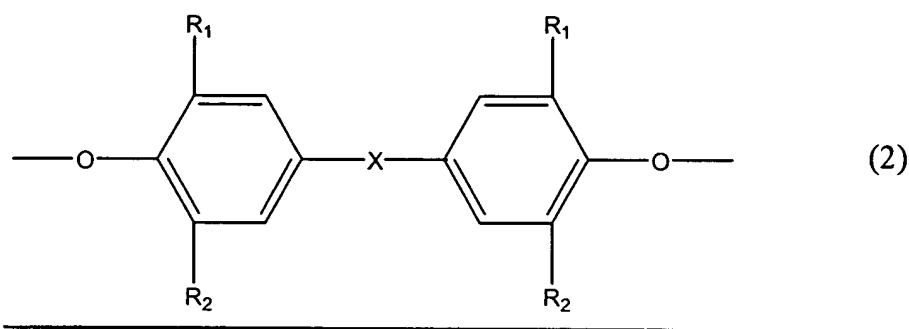
1. (Currently Amended) A photo- or heat-curable resin composition for forming a resin insulation layer in a printed wiring board comprising a resin-forming component and 0.1 to 1 ~~0.01-5~~ parts by weight of an inorganic filler with its average particle diameter ~~controlled~~ in the range of 5 nm-0.5 μ m per 100 parts by weight of the resin-forming component

wherein the resin-forming component comprises:

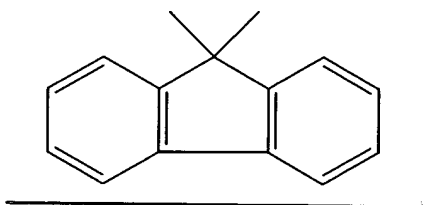
(A) 100 parts by weight of a photopolymerizable unsaturated compound represented by the following general formula (1)



wherein R is a hydrogen atom or a methyl group, A is a group represented by the formula (2)



(wherein R_1 and R_2 are independently hydrogen, an alkyl group with 1-5 carbon atoms, or a halogen), X is $-\text{CO}-$, $-\text{SO}_2-$, $-\text{C}(\text{CF}_3)_2-$, $-\text{Si}(\text{CH}_3)_2-$, $-\text{CH}_2-$, $-\text{O}-$, $-\text{S}-$,



or a direct bond, Y and Z are respectively the residue of a polycarboxylic acid or its acid anhydride, and m and n are the number of repeating units at a molar ratio m/n 0/100 - 100/0,

(B) 0-50 parts by weight of a compound containing an epoxy group,

(C) 0-10 parts by weight of a photopolymerization initiator or sensitizer;

wherein the inorganic filler is silica sol with its average particle diameter in the range of 5 nm-0.5 μm per 100 parts by weight based on the combined weight of resin forming components

which consists of at least one selected from a photo- or heat-polymerizable unsaturated compound and a condensable compound and the compound containing an epoxy group (B) and a curing agent of the compound (B).

2. (Canceled)

3. (Canceled)

4. (Currently Amended) A photo- or heat-curable resin composition as described in claim 1 wherein the resin-forming component comprises (A) 30-80% by weight of a photopolymerizable unsaturated compound, (B) 10-50% by weight of a compound containing an epoxy group, and 10-40% by weight of a polyfunctional acrylate, the inorganic filler is ~~composed of~~ silica sol with its average particle diameter ~~controlled~~ in the range of 10-100 nm, and the composition is formulated from 100 parts by weight of the resin-forming component, 0.1-1 part by weight of the inorganic filler as silica, and 1-5 parts by weight of the photopolymerization initiator.

5. (Original) A multilayer printed wiring board wherein a resin insulation layer is formed by the cured product of a

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photo- or heat-curable resin composition as described in claim

1.